

MATERIAL DATA SHEET



SMD Diodes Specialist

Material #	CPDH6 Series	
Product Line	SOT-563	
Date	2009/6/18	
Rev. date	B	

COMPONENT DETILS

No.	Construction element	Material group	Material weight (mg)	Material	CAS if applicable	Average mass (%)	Sum(%)	Traces
1	Lead Frame	SDI	1.098	Manganese	7439-96-5	<0.3%	32.37%	
				Nickel	7440/2/1	8.5%~10.5%		
				Iron	7439-89-6	<0.6%		
				Tin	7440-31-5	1.8%~2.8%		
				Zinc	7440-66-6	<0.5%		
				Lead	7439-92-1	<0.05%		
				Copper	7440-50-8	Bal.		
				Silver	7740-22-4	Surface Plating		
2	Wire	Heraeus	0.029	Aurum	7440-57-5	100.00%	0.85%	
3	Mold Compound	HuaWei	2.008	Silica Fused	60676-86-0	83.00%	59.20%	
				Epoxy resin	29690-82-2	10.00%		
				Phenolic Resin	9003-35-4	6.50%		
				Carbon Black	1333-86-4	0.50%		
5	Wafer	Wafer	0.2000	Silicon (Si)	7440-21-3	100.00%	5.90%	
5	Plating	YSTIN	0.057	Tin	7440-31-5	100.00%	1.68%	
		Total weight	3.392					